Product Change Notification: MFOL-08KSAS331

Date:

12-Oct-2025

Product Category:

32-Bit Microcontrollers

Notification Subject:

CCB 7564 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected ATSAMC20G15A, ATSAMC20G16A, ATSAMC20G17A, ATSAMC20G18A, ATSAMC21G15A, ATSAMC21G16A, ATSAMC21G17A, ATSAMC21G18A, ATSAMD20G14, ATSAMD20G15, ATSAMD20G16, ATSAMD20G17, ATSAMD20G18, ATSAMD21G15, ATSAMD21G16x, ATSAMD21G17x, ATSAMD21G18, ATSAML21G16B, ATSAML21G17B and ATSAML21G18B device families available in 48L VQFN (7x7x0.9mm) package at MP3A assembly site.

Affected CPNs:

MFOL-08KSAS331_Affected_CPN_10122025.pdf
MFOL-08KSAS331_Affected_CPN_10122025.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected ATSAMC20G15A, ATSAMC20G16A, ATSAMC20G17A, ATSAMC20G18A, ATSAMC21G15A, ATSAMC21G16A, ATSAMC21G17A, ATSAMC21G18A, ATSAMD20G14, ATSAMD20G15, ATSAMD20G16, ATSAMD20G17, ATSAMD20G18, ATSAMD21G15, ATSAMD21G16x, ATSAMD21G17x, ATSAMD21G18, ATSAML21G16B, ATSAML21G17B and ATSAML21G18B device families available in 48L VQFN (7x7x0.9mm) package at MP3A assembly site.

Pre and Post Summary Changes:

	Pre Change	**Post Change**

Assembly Site	Microchip Technology Inc. (MPHIL-3) (MP3A)	Microchip Technology Inc. (MPHIL-3) (MP3A)
Wire Material	Au	CuPdAu
Die Attach Material	3280 (PFAS)	3280NP (PFAS Free)
Molding Compound Material	G700LTD	G700LTD
Lead-Frame Material	C194	C194

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 31 October 2025 (date code: 2544)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	May 2025					>	**October 2025**				
Work Week	18	19	20	21	22		40	41	42	43	44
Initial PCN Issue Date			x								
Qual Report Availability								x			
Final PCN Issue Date								x			
Estimated Implementation Date											x

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: May 16, 2025: Issued initial notification.
October 12, 2025: Issued final notification. Attached the Qualification Report. Provided estimated first ship date is to be on October 31, 2025.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_MFOL-08KSAS331_Qual Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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